

Checklist for thin film inquiry

Customer:	Project name:
	<input type="checkbox"/> Sample <input type="checkbox"/> Series
Requested quantity:	

Data:
 Customer files: DXF GDS Gerber

Definition of conductive layers:

Gold Technology :
 Top layer: TaN/TiW/Au (standard) TiW/Au
 Bottom layer: TiW/Au (including offset 50µm) None
 Other:

Copper Technology :
 Top layer: NiCr/Ti/Cu/Ni/Au (standard) Ti/Cu/Ni/Au
 Bottom layer: Ti/Cu/Ni/Au (including offset 50µm) None
 Other:

Conductive Layer thickness: 3µm 5µm 10µm other:
 Tolerance of conductive layer thickness: ±1µm ±2µm other:

Details:

Material: Al2O3 AlN Other:
 Thickness: 5mil 15mil 25mil 40mil other:
 Surface: as fired polished other:
 Circuit dimensions: [mm] X : Y :
 Tolerance of structure: ±3µm ±5µm ±10µm other:
 Structure measurement point: defined in customer drawing set by AFT
 Separating: Dicing (Offset 50µm, Dicing line 150µm) Laser cutting None
 Sheet resistance: [Ω/□] 20Ω +0%/ -30% 50Ω +0%/ -30% 100Ω +0%/ -30%
 other:
 Trimming of resistor: yes no (Tolerance +0%/ -30%)
 Tolerance of resistors (trimmed): ±1% ±1,5% ±5% other:
 Holes: not metallized metallized filled none
 Packing style: Waffle Pack Blister Tape Other:
 Additional requests:

Technical release

Customer Signature:	AFT Signature:
---------------------	----------------

For internal use:

Item-No.:	Masks availability (quantity):
RFQ-No.:	RFQ-Date:
Agent:	